

NPN medium power transistors**BCP54; BCP55; BCP56****FEATURES**

- High current (max. 1 A)
- Low voltage (max. 80 V).

APPLICATIONS

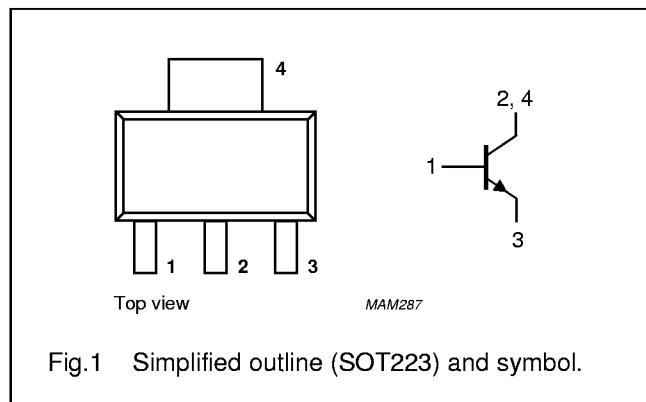
- Switching.

DESCRIPTION

NPN medium power transistor in a SOT223 plastic package. PNP complements: BCP51, BCP52 and BCP53.

PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage BCP54 BCP55 BCP56	open emitter	—	45	V
V_{CEO}	collector-emitter voltage BCP54 BCP55 BCP56	open base	—	60	V
V_{EBO}	emitter-base voltage	open collector	—	100	V
I_C	collector current (DC)		—	45	V
I_{CM}	peak collector current		—	60	V
I_{BM}	peak base current		—	80	V
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	—	1.33	W
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		—	150	°C
T_{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

NPN medium power transistors

BCP54; BCP55; BCP56

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	94	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		13	K/W

Note

1. Device mounted on printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm².
For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

CHARACTERISTICS

$T_{amb} = 25^\circ C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = 30\text{ V}$	—	—	100	nA
		$I_E = 0; V_{CB} = 30\text{ V}; T_j = 125^\circ C$	—	—	10	μA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = 5\text{ V}$	—	—	100	nA
h_{FE}	DC current gain	$I_C = 5\text{ mA}; V_{CE} = 2\text{ V}$	25	—	—	
		$I_C = 150\text{ mA}; V_{CE} = 2\text{ V}$	63	—	250	
		$I_C = 500\text{ mA}; V_{CE} = 2\text{ V}$	25	—	—	
h_{FE}	DC current gain BCP55-10; 56-10 BCP54-16; 55-16; 56-16	$I_C = 150\text{ mA}; V_{CE} = 2\text{ V}$	—	—	160	
			63	—	250	
			100	—	—	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 0.5\text{ A}; I_B = 50\text{ mA}$	—	—	500	mV
V_{BE}	base-emitter voltage	$I_C = 0.5\text{ A}; V_{CE} = 2\text{ V}$	—	—	1	V
f_T	transition frequency	$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}$	—	130	—	MHz
$\frac{h_{FE1}}{h_{FE2}}$	DC current gain ratio of the complementary pairs	$ I_C = 150\text{ mA}; V_{CE} = 2\text{ V}$	—	—	1.6	

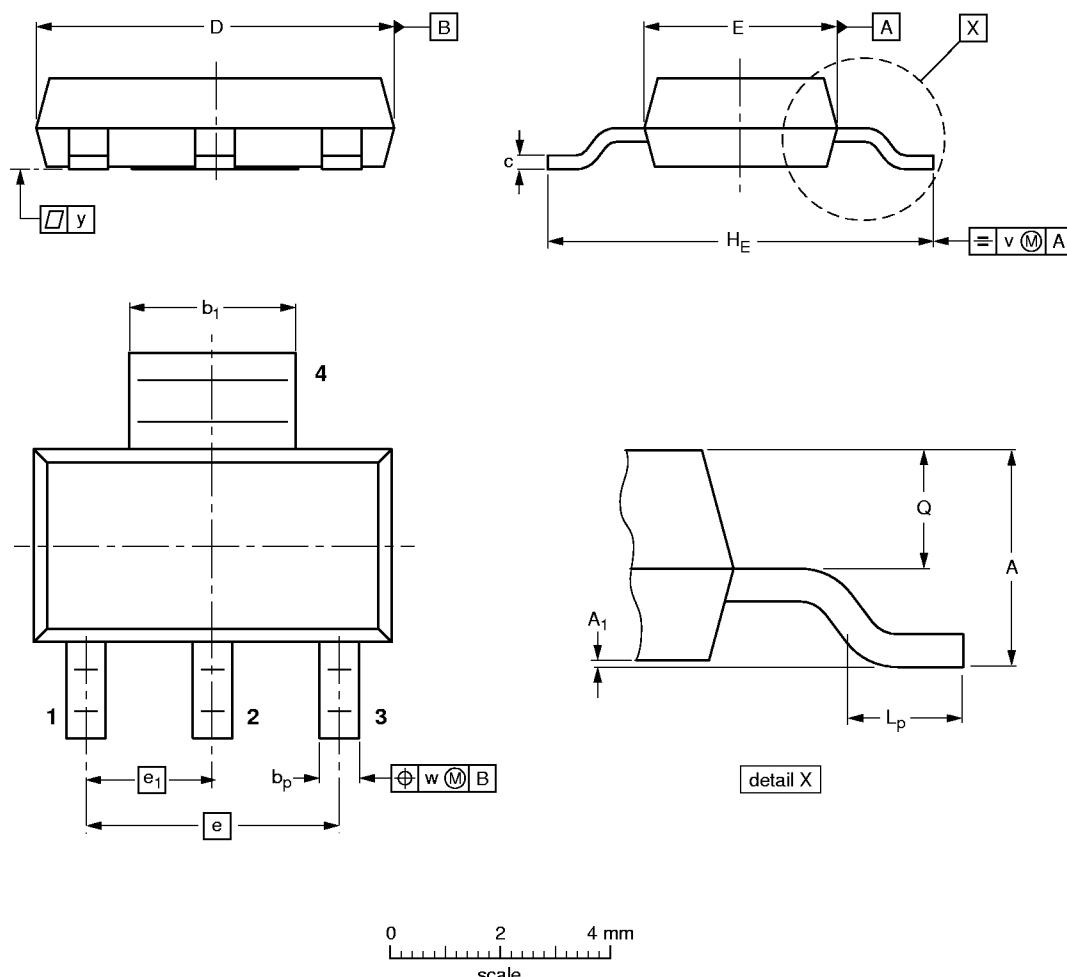
NPN medium power transistors

BCP54; BCP55; BCP56

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.8	0.10	0.80	3.1	0.32	6.7	3.7	4.6	2.3	7.3	1.1	0.95	0.2	0.1	0.1
	1.5	0.01	0.60	2.9	0.22	6.3	3.3			6.7	0.7	0.85			

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT223						96-11-11 97-02-28